



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20190904001.2
Bubble Wrap removal for Select MSL1 Device(s)
Change Notification / Sample Request
Re-issue with page 2 correction

Date: September 23, 2019
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services


20190904001
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN65HVD1040QDRQ1	null
SN65HVD1050AQRQ1	null
SN65HVD1781QDRQ1	null
SN65HVDA1050AQRQ1	null
SN65HVDA195QDRQ1	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190904001.2		PCN Date:	Sept 23, 2019	
Title:	Bubble Wrap removal for Select MSL1 Device(s)				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Mar 23, 2020		Estimated Sample Availability:	Date provided at sample request	
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
This change notification is to announce the Bubble wrap removal for select MSL1 devices listed in the "Product Affected" Section.					
		From		To	
	Packing Description	With Bubble Wrap		Without Bubble Wrap	
	Visual comparison				
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp		
Changes to product identification resulting from this PCN:					
None					
Product Affected:					

ADS1000A0QDBVRQ1	PCM1794AQDBRQ1	SN74HC4060QDRQ1	TPIC44L02QDBRVS
ADS1000A1QDBVRQ1	PH14T245QPWRQ1	SN74HC573AQDWRQ1	TPIC46L01DBR
ADS1259QPWRQ1	PSN3257QPWRQ1	SN74HCS00QDRQ1	TPIC46L01DBRG4
CD40109BQNSRQ1	SN0210047DBR	SN74HCS02QDRQ1	TPIC46L02DBR
CDC2351QDBR	SN0210048DBR	SN74HCS03QDRQ1	TPIC46L02DBRG4
CDC2351QDBRG4	SN0301022BDBR	SN74HCS04QDRQ1	TPS2211IDBRG4AN
DAC900TPWRQ1	SN0311054DBR	SN74HCS05QDRQ1	TPS92691QPWPTQ1
HVDA5405QDRQ1	SN0506082DR	SN74HCS08QDRQ1	TXS0104EQPWRQ1
HVDA5415QDRQ1	SN3257QPWRQ1	SN74HCS09QDRQ1	UC2843AQDR
HVDA541QDRQ1	SN65HVD1040AQDRCT	SN74HCS10QDRQ1	UC2844AQD8R
HVDA5425QDRQ1	SN65HVD1040AQDRQ1	SN74HCS11QDRQ1	UC2844AQDR
HVDA542QDRQ1	SN65HVD1040QDRQ1	SN74HCS125QDRQ1	UCC27322QDRQ1
INA253A1QPWRQ1	SN65HVD1040QDRSV	SN74HCS126QDRQ1	UCC27524AQDRQ1
INA253A2QPWRQ1	SN65HVD1050AQDRCT	SN74HCS14QDRQ1	UCC2801QDRQ1
INA253A3QPWRQ1	SN65HVD1050AQDRDL	SN74HCS20QDRQ1	UCC2802QDRQ1
LM26001QMXAX/J7002755	SN65HVD1050AQDRQ1	SN74HCS21QDRQ1	UCC2803QDRQ1
LM26001QMXAX/NOPB	SN65HVD1050QDRQ1	SN74HCS266QDRQ1	UCC2803QDRSV
LM26003QMHX/NOPB	SN65HVD1050QDRSV	SN74HCS27QDRQ1	UCC2804QDRQ1
LM3424QMHX/NOPB	SN65HVD1780QDRQ1	SN74HCS32QDRQ1	UCC2805QDRQ1
LM3492QMHX/NOPB	SN65HVD1781AQDRQ1	SN74HCS4075QDRQ1	UCC2808AQDR-1G4Q1
LMT57FSPWRQ1	SN65HVD1781QDRQ1	SN74HCS7002QDRQ1	UCC2808AQDR-1Q1
LMT57TSPWRQ1	SN65HVD1782QDRQ1	SN74HCS7266QDRQ1	UCC2808AQDR-2G4Q1
MLA00348DRG4	SN65HVDA1040AQDRKN	SN74HCS72QDRQ1	UCC2808AQDR-2Q1
MLA00352DBVR	SN65HVDA1040AQDRQ1	SN74HCS74QDRQ1	UCC2813QD-5MH
MSP430G2333IPW8RQ1	SN65HVDA1040BQDRQ1	SN74HCS86QDRQ1	UCC2813QDR-1Q1
MSP430G2453IPW0RQ1	SN65HVDA1050AQDRQ1	TCAN1043DRQ1	UCC2813QDR-2Q1
MSP430G2453IPW8RQ1	SN65HVDA195AQDRQ1	TCAN1046DRQ1	UCC2813QDR-3Q1
MSP430G2553IPW0RQ1	SN65HVDA195QDRQ1	TPIC44L01DBR	UCC2813QDR-4Q1
MSP430G2553IPW8RQ1	SN74AHCT244QDWRQ1	TPIC44L02DBR	UCC2813QDR-5Q1
OPA4364AQDRQ1	SN74AHCT245IDBRVS	TPIC44L02DBRG4	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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